

Electronic Patent Application Fee Transmittal

Application Number:	10593152
Filing Date:	18-Sep-2006
Title of Invention:	ELECTRODEPOSITED COPPER FOIL WITH CARRIER FOIL ON WHICH A RESIN LAYER FOR FORMING INSULATING LAYER IS FORMED, COPPER-CLAD LAMINATE, PRINTED WIRING BOARD, METHOD FOR MANUFACTURING MULTILAYER COPPER-CLAD LAMINATE, AND METHOD FOR MANUFACTURING PRINTED WIRING BOARD
First Named Inventor/Applicant Name:	Seiji Nagatani
Filer:	Arnold Turk/Sean Shoolbraid
Attorney Docket Number:	3209-124

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1810